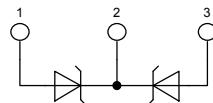


**Schottky Diode Gen 2**

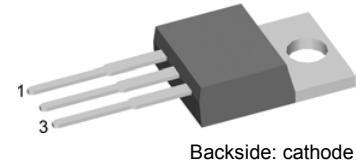
High Performance Schottky Diode  
Low Loss and Soft Recovery  
Common Cathode

**Part number**

DSA 60 C 150 PB



**V<sub>RRM</sub> = 150 V**  
**I<sub>FAV</sub> = 2x 30 A**  
**V<sub>F</sub> = 0.80 V**

**Features / Advantages:**

- Very low V<sub>f</sub>
- Extremely low switching losses
- low I<sub>rm</sub> values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

**Applications:**

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

**Package:**

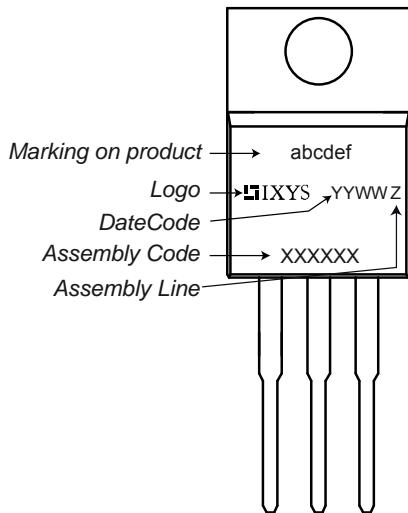
- Housing: TO-220
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

Symbol	Definition	Conditions			Ratings		
					min.	typ.	max.
V <sub>RRM</sub>	max. repetitive reverse voltage			T <sub>VJ</sub> = 25 °C			150 V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 150 V		T <sub>VJ</sub> = 25 °C		0.45 mA	
		V <sub>R</sub> = 150 V		T <sub>VJ</sub> = 125 °C		5 mA	
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 30 A		T <sub>VJ</sub> = 25 °C		0.93 V	
		I <sub>F</sub> = 60 A				1.09 V	
		I <sub>F</sub> = 30 A		T <sub>VJ</sub> = 125 °C		0.80 V	
		I <sub>F</sub> = 60 A				0.98 V	
I <sub>FAV</sub>	average forward current	rectangular	d = 0.5	T <sub>C</sub> = 150 °C		30 A	
V <sub>F0</sub> r <sub>F</sub>	threshold voltage slope resistance } for power loss calculation only			T <sub>VJ</sub> = 175 °C		0.55 V	
						6 mΩ	
R <sub>thJC</sub>	thermal resistance junction to case					0.85 K/W	
T <sub>VJ</sub>	virtual junction temperature				-55	175 °C	
P <sub>tot</sub>	total power dissipation			T <sub>C</sub> = 25 °C		175 W	
I <sub>FSM</sub>	max. forward surge current	t = 10 ms (50 Hz), sine		T <sub>VJ</sub> = 45 °C		200 A	
C <sub>J</sub>	junction capacitance	V <sub>R</sub> = 12 V; f = 1 MHz		T <sub>VJ</sub> = 25 °C	289 pF		

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
$I_{RMS}$	RMS current	per terminal <sup>1)</sup>			35 A
$R_{thCH}$	thermal resistance case to heatsink			0.50	K/W
$T_{stg}$	storage temperature		-55		150 °C
<b>Weight</b>				2 g	
$M_D$	mounting torque		0.4		0.6 Nm
$F_c$	mounting force with clip		20		60 N

1)  $I_{RMS}$  is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2).  
In case of (1) and a common cathode/anode configuration with a non-isolated backside,  
the current capability can be increased by connecting the backside.

### Product Marking



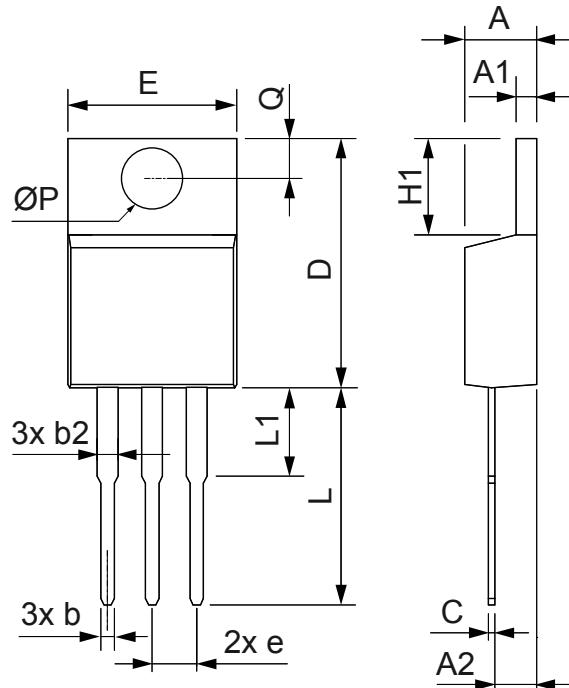
### Part number

D = Diode  
S = Schottky Diode  
A = low VF  
60 = Current Rating [A]  
C = Common Cathode  
150 = Reverse Voltage [V]  
PB = TO-220AB (3)

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSA 60 C 150 PB	DSA60C150PB	Tube	50	509198

Similar Part	Package	Voltage class
DSA50C150HB	TO-247AD (3)	150

## Outlines TO-220



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.32	4.82	0.170	0.190
A1	1.14	1.39	0.045	0.055
A2	2.29	2.79	0.090	0.110
b	0.64	1.01	0.025	0.040
b2	1.15	1.65	0.045	0.065
C	0.35	0.56	0.014	0.022
D	14.73	16.00	0.580	0.630
E	9.91	10.66	0.390	0.420
e	2.54	BSC	0.100	BSC
H1	5.85	6.85	0.230	0.270
L	12.70	13.97	0.500	0.550
L1	2.79	5.84	0.110	0.230
ØP	3.54	4.08	0.139	0.161
Q	2.54	3.18	0.100	0.125

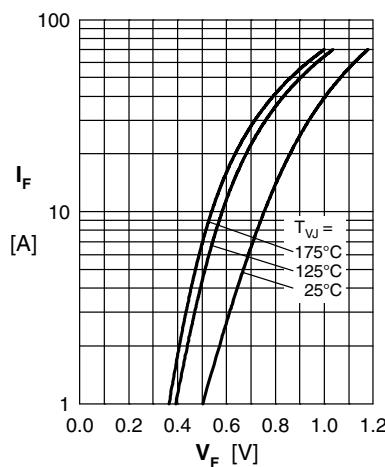


Fig. 1 Maximum forward voltage drop characteristics

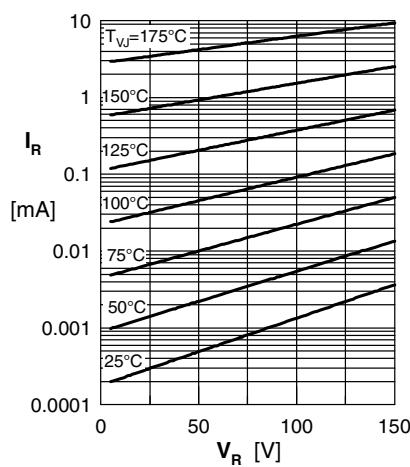


Fig. 2 Typ. reverse current  $I_R$  vs. reverse voltage  $V_R$

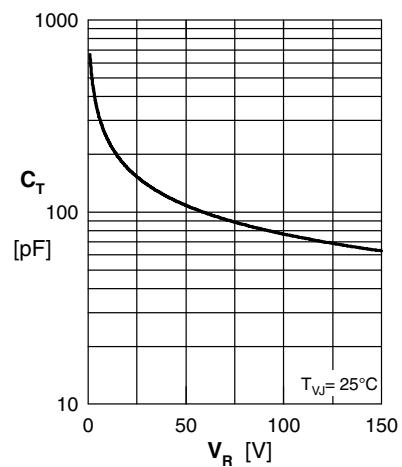


Fig. 3 Typ. junction capacitance  $C_T$  vs. reverse voltage  $V_R$

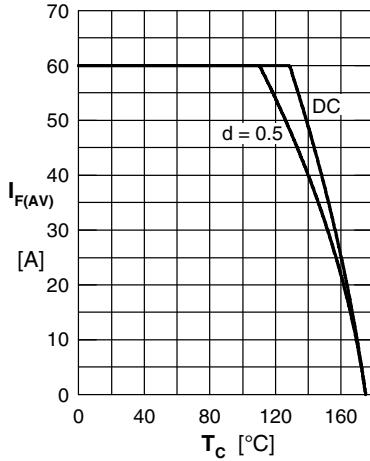


Fig. 4 Average forward current  $I_{F(AV)}$  vs. case temperature  $T_C$

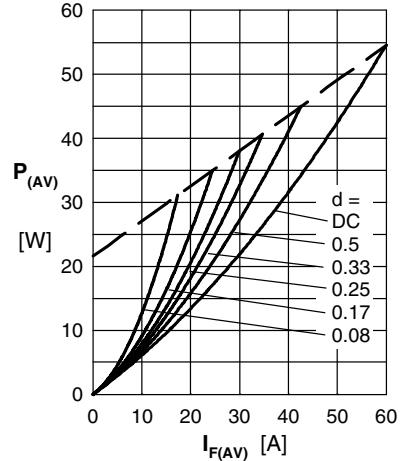


Fig. 5 Forward power loss characteristics

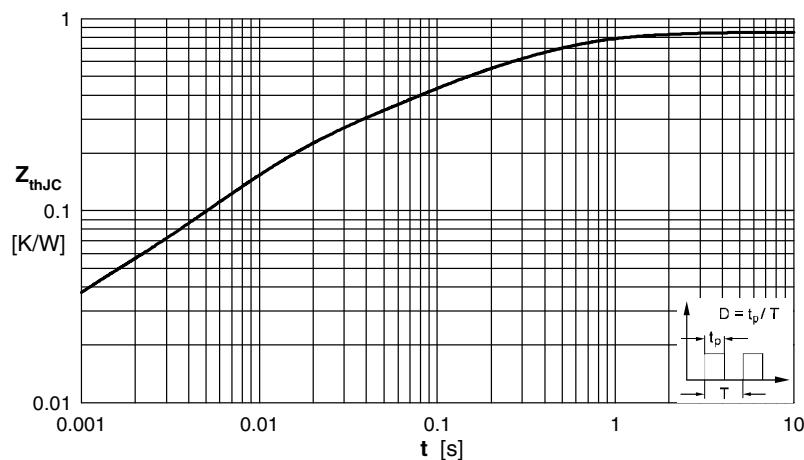


Fig. 6 Transient thermal impedance junction to case at various duty cycles

i	$R_{thi}$ [K/W]	$t_i$ [s]
1	0.02326	0.0005
2	0.1539	0.011
3	0.2031	0.072
4	0.3892	0.34
5	0.08053	1.5